

IN THE CLAIMS

Please amend the claims as follows.

1. - 7. (Canceled)

8. (Currently Amended) A method for dicing workpieces, comprising:
scribing a workpiece with a laser to form a scribe having a depth of at least 25 microns;
and
completely cutting through the workpiece along the scribe with a mechanical cutter that follows the scribe created by the laser.

9. (Original) The method of claim 8, wherein scribing includes setting the laser to have an average power of about 300 watts and a maximum refresh rate of 3,000 Hz.

10. (Original) The method of claim 8, wherein completely cutting includes engaging the wafer at the scribe with a saw.

11. (Previously Presented) The method of claim 10, wherein engaging the wafer includes sawing the wafer with a nickel-diamond cutting surface.

12. (Original) The method of claim 8, wherein scribing includes scribing the wafer with a yttrium-aluminum-garnet (YAG) laser.

13. (Currently Amended) A method for dicing workpieces, comprising:
scribing a workpiece with a laser along a saw street to form a scribe having a depth of at least 25 microns; and
completely cutting through the workpiece with a mechanical cutter in the same saw street being scribed by the laser, wherein the laser and the mechanical cutter simultaneously contact the workpiece.

14. (Original) The method of claim 13, wherein completely cutting includes fixing the mechanical cutter at a set distance behind the laser.
15. (Original) The method of claim 14, wherein scribing includes setting the laser to have an average power of about 300 watts and a maximum refresh rate of 3,000 Hz.
16. (Currently Amended) A method for dicing workpieces, comprising:
moving a workpiece relative to a laser;
scribing a workpiece with the laser to form a scribe having a depth of at least 25 microns;
and
completely cutting through the workpiece along the scribe with a mechanical cutter that follows a scribe created by the laser.
17. (Original) The method of claim 16, wherein moving includes moving the workpiece at a speed of 120 mm/sec.
18. (Original) The method of claim 17, wherein scribing includes setting the laser to have an average power of about 300 watts and a maximum refresh rate of 3,000 Hz.
19. (Original) The method of claim 16, wherein moving a workpiece relative to a laser includes holding the laser stationary.
20. (Original) The method of claim 16, wherein completely cutting through the workpiece includes cutting the workpiece with a nickel coated blade.
21. (Previously Presented) The method of claim 16, wherein cutting includes the mechanical cutter directly following the laser in the scribe at a fixed distance.
22. (Previously Presented) The method of claim 13, wherein cutting includes the laser and mechanical cutter simultaneously engaging a same saw street.

23. (Previously Presented) The method of claim 9, wherein cutting includes the mechanical cutter directly following the laser in the scribe at a fixed distance.
24. (Currently Amended) A method for dicing an integrated circuit substrate, comprising:
moving a substrate relative to a laser;
partially ablating a saw street in the substrate with a laser to form a scribe having a depth of at least 25 microns; and
completely cutting through the saw street of the substrate along the scribe with a mechanical cutter that follows the scribe created by the laser.
25. (Previously Presented) The method of claim 24, wherein cutting includes the mechanical cutter directly following the laser at a fixed distance.
26. (Previously Presented) The method of claim 24, wherein moving includes moving the substrate at a speed of about 120 mm/sec.
27. (Previously Presented) The method of claim 24, wherein ablating includes setting the laser to have an average power of about 300 watts and a maximum refresh rate of 3,000 Hz.